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PN - JP51018245 A 19760213  
PNFP - JP54008458B B 19790416  
- JP976727C C 19791030  
FI - B23K35/363&A; B23K35/363&C; H05K3/34&503Z  
FT - 5E319/AC01; 5E319/CC23; 5E319/CD01; 5E319/CD21; 5E319/CD52; 5E319/GG20  
PA - (A)  
- TAMURA KAKEN CO LTD  
IN - (A)  
- NAKAMURA KOZO  
AP - JP19740089115 19740805  
PR - JP19740089115 19740805  
DT - I

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AN - 1976-23519X [13]  
TI - Delustering [ ] for soldering printed circuits - contains inorg oxide powder and/or org acid metal salt powder  
AB - An inorg. oxide fine powder and/or org. acid metal salt fine powder is/are added to a flux base consisting of rosin type resin, activator and org. solvent. The inorg. oxide may be silicic acid anhydride, clay, titanium oxide, silica gel, etc. and the org. acid metal salt may be aluminum stearate, aluminum oleate, aluminum palmitate, etc. The surface of the welded areas is delustered and non-corrosive.  
IW - DELUSTERED FLUX SOLDER PRINT CIRCUIT CONTAIN OXIDE POWDER ACID METAL SALT  
PN - JP51018245 A 19760213 DW197613  
JP54008458B B 19790416 DW197919  
ICAI - B23K35/362; B23K35/363; H05K3/34  
ICCI - B23K35/362; H05K3/34  
MC - L03-D03F L03-H04E  
DC - L03 M23  
- P55  
- V04  
PA - (TAMU-N) TAMURA KAKEN CO LTD  
AP - JP19740089115 19740805